Amendments to the Claims

Claims 1-27 (Cancelled).

28. (Currently Amended) A hole plugging method for plugging holes in a printed circuit board, comprising:

filling a solder resist or insulating resin in spaces between surface side circuit patterns by moving a squeegee under the condition of being abutted on an upper surface of a circuit pattern formed on the surface of a printed circuit board ~~and formed in the board~~ and in a hole for electrically connecting the circuit pattern formed on the surface of the board and the circuit pattern formed in the board or for connecting the circuit patterns on the both side surfaces and by moving the squeegee ~~wile~~ while being abutted directly to the surface of the printed circuit board; ~~and~~

wherein ~~filling~~ the solder resist or insulating resin in the spaces among the surface side circuit patterns is filled to the same height as the upper surface of the circuit patterns.

29-50. (Canceled)

51. (Currently Amended) A plugging method for a printed circuit board having a plurality of first circuit patterns with via holes and through holes formed on a surface of the board, comprising:

filling a solder resist or ~~insulting~~ insulating resin in spaces between the first circuit patterns by moving a squeegee under the condition of being abutted directly on an upper surface of the first circuit patterns; and

plugging the solder ~~resister or insulting~~ resist or insulating resin into the via holes and/or the through holes by moving the squeegee under the condition of being abutted directly on the upper surface of the via holes and/or the through holes;

wherein the solder resist or insulating resin filled in the spaces among the surface side of the first circuit patterns is filled to the same height as the upper surface of the first circuit patterns.

52. (Previously Presented) The method of claim 51, wherein the printed circuit board further includes one or more via holes formed to electrically connect between the first circuit patterns and a plurality of second circuit patterns formed inside the board, and/or one or more through holes formed to electrically interconnect both the upper and lower surface of the first circuit patterns.

53. (Currently Amended) The method of claim 51, wherein the solder resist or insulating resin ~~filled in the spaces among the surface side circuit patterns~~ is filled to the same height as the upper surface of ~~the first~~ circuit patterns ~~of the via holes~~.

54. (Cancelled).

55. (Currently Amended) The method of claim ~~52~~ 51, comprising the steps of:

a first step of plugging the solder resist or insulating resin in one portion of the via holes and/or the through holes; and

a second step of completely plugging the solder resister or insulating resin in the whole portion of the via holes ~~and/or the through holes by moving the squeegee under the condition of being abutted on the surface of the via holes and/or the through holes~~.

56. (Previously Presented) The method of claim 55, wherein in the second plugging step the solder resist or insulting resin is plugged in the via holes and/or the through holes by moving the squeegee in the opposite direction to the moving direction of the squeegee in the first plugging step.

57. (Previously Presented) The method of claim 55, wherein in the second plugging step the solder resist or insulting resin is plugged in the hole by moving the squeegee in the same direction to the moving direction of the squeegee in the first plugging step.

58. (Currently Amended) The method of claim 52, wherein the solder resist or insulating resin is coated only on an area exposed by a mask for selectively exposing the first circuit patterns at a predetermined interval ~~or on the via holes and/or the through holes~~.

59. (Cancelled).

60. (New) A plugging method for a printed circuit board having a plurality of first circuit patterns formed on a surface of the board, comprising:

filling a solder resist or insulating resin in spaces between the first circuit patterns by moving a squeegee under the condition of being abutted directly on an upper surface of the first circuit patterns; and

plugging the solder resist or insulating resin into via holes by moving the squeegee under the condition of being abutted directly on the upper surface of the via holes,

wherein the plugging step further comprising,

a first step of plugging the solder resist or insulating resin in one portion of the via holes; and

a second step of completely plugging the solder resist or insulating resin in the whole portion of the via holes.

61. (New) A hole plugging method for plugging holes in a printed circuit board, comprising:

filling a solder resist or insulating resin in spaces between surface side circuit patterns by moving a squeegee under the condition of being abutted on an upper surface of a circuit pattern formed on the surface of a printed circuit board and in a hole for electrically connecting the circuit pattern formed on the surface of the board and the circuit pattern formed in the board or for connecting the circuit patterns on the both side surfaces and by moving the squeegee while being abutted directly to the surface of the printed circuit board, wherein the filling step further comprising,

a first step of plugging the solder resist or insulating resin in one portion of the hole by moving the squeegee under the condition of being abutted on the upper surface of the hole; and

a second step of completely plugging the solder resist or insulating resin in the whole portion of the hole by moving the squeegee under the condition of being abutted on the upper surface of the hole;

wherein the solder resist or insulating resin in the spaces among the surface side circuit patterns is filled to the same height as the upper surface of the circuit patterns.